

### ABSTRACT OF DISCLOSURE

Microelectronic packages including a microelectronic die disposed within a recess in a heat spreader and build-up layers of dielectric materials and conductive traces are then fabricated on the microelectronic die and the heat spreader to form the microelectronic package, and methods for the fabrication of the same, including methods to align the microelectronic die within the heat spreader. In another embodiment, a microelectronic die is disposed on a heat spreader which has a filler material disposed therearound and build-up layers of dielectric materials and conductive traces are then fabricated on the microelectronic die and the filler material to form the microelectronic package, and methods for the fabrication of the same, including methods to align the microelectronic die on the heat spreader.

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